

# WAFER-5820/5822

3.5" Disk Size GX1-300 Embedded Board, With 10/100Mbps Ethernet, LCD/CRT VGA, CPU & Audio

IEI is proud to launch MS Windows CE on our embedded solutions. Windows CE 3.0 is also available by request.

#### What is Windows CE?

Windows CE is a compact, scalable and flexible operating system, which stems from the MS Windows OS family. MS Windows 3.0 adds real-time feature and more powerful functions and is expected to greatly enhance the system's applicability for industrial use.

#### What are the benefits with Windows CE?

Windows CE was developed for the following reasons:

1. To provide a common base for software applications.
2. To provide a modular design for customization.
3. To minimize memory footprint and maximize system performance.

#### What does IEI offer to its customers?

IEI offers a dedicated Windows CE technical team, which provides a complete emulation environment for building Windows CE image by the combination of either the CE 2.12 kernel, CE 3.0 kernel, system drivers and CE-based applications. Customers receive total solution from IEI including OS licensing, driver support, image building and system testing. In addition, we welcome customers' inquiry, pertaining to Windows CE, on product software/hardware compatibility, system integration testing and certification.



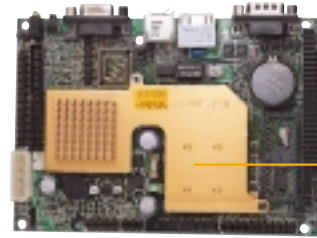
WAFER-5820/5822



300MHz NOW!



Wafer-5820 New Version +5V only



Best Heat Sink Design

### Ordering Information:

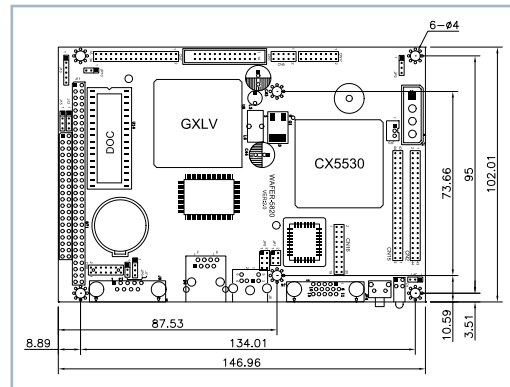
#### WAFER-5820-300-R3

3.5" disk size 300MHz embedded board with VGA & 10/100Mbps Ethernet

#### WAFER-5822-300

3.5" disk size 300MHz embedded board with VGA, 10/100Mbps Ethernet & DIO/TV-out

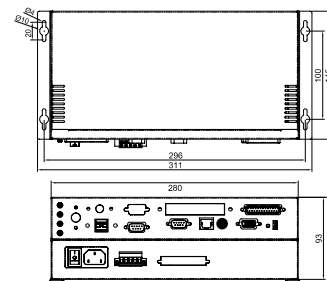
### Dimensions:



### EB-1800 Embedded Chassis for Wafer-5820/5822

- Support one PC/104 module space
- Equipped with ACE-855A PSU
- Optional ACE-855/890 series PSU
- Support two 2.5" drive bay

### Dimensions:



### Specifications

- **CPU** : Embedded National Semiconductor™ low power consumption Geode GX1 300MHz
- **BIOS** : Award PnP Flash BIOS
- **System Chipset** : National Semiconductor™ Geode™ GXLV/GX1 + CS5530A
- **System Memory** : One 144-pin SO-DIMM socket up to 512MB SDRAM (Wafer-5820), 256MB (Wafer-5822)
- **Display** :
  - Built-in CS5530A chipset, supports TFT LCD & CRT display
  - V-RAM : Share with system memory (up to 4MB), setting in BIOS
  - Resolution : 1280 x 1024 (256 colors)
  - Connector : DB-15 for CRT display  
44-pin pin-header for TFT LCD  
20-pin pin-header for LCD LVDS interface(WAFER-5820)  
TV Out (Both NTSC & PAL) (WAFER-5822)
- **Ethernet** : Realtek RTL8139 10/100Mbps Ethernet chip with RJ-45 connector
- **SSD** : One DiskOnChip™ socket
- **Audio** : AC'97 compliant Audio CODEC
- **I/O** :
  - 1 x RS-232 port & 1 x RS-232/422/485 selectable port with auto-direction function (WAFER-5820)
  - 2 x RS-232 ports (WAFER-5822)
  - 1 x parallel port (support SPP/EPP/ECP mode)
  - 2 x USB 1.1 (pin header)
  - 1 x IrDA port
  - 1 x FDD port
  - 1 x ATA-33 IDE channel (44-pin pin-header)
- **WDT**: software programmable, support 1~ 255 sec. system reset
- **Digital I/O** : 4 x DI & 4 x DO, TTL Level (WAFER-5822)
- **One PC/104 expansion connector for add-on cards**
- **Power Consumption** : +5V@2A, +12V@100mA (GXLV 233MHz CPU and 32MB SDRAM), Wafer-5820-300-R3 (+5V only)
- **Operating temperature** : 0°~60°C
- **Relative humidity** : 5~95%, non-condensing
- **GW**: 700g